

Vapor Deposition Production Coating System ✓

BACKGROUND OF THE INVENTION

1. Technical Field

This invention relates to vapor deposition apparatus in general, and to production systems in particular.

2. Background Information

Vapor deposition as a means for applying a coating to a substrate is a known art that includes processes such as chemical vapor deposition, physical vapor deposition, and cathodic arc vapor deposition. Chemical vapor deposition involves introducing reactive gaseous elements into a deposition chamber containing one or more substrates to be coated. Physical vapor deposition involves providing a source material and a substrate to be coated in a evacuated deposition chamber. The source material is converted into vapor by an energy input, such as heating by resistive, inductive, or electron beam means. Cathodic arc vapor deposition involves a source material and a substrate to be coated placed in an evacuated deposition chamber containing only a relatively small amount of gas. An arc, traveling between the cathode and an anode, vaporizes the cathode into a plasma containing atoms, molecules, ions, electrons, and particles. Positively charged ions liberated from the cathode are attracted toward any object within the deposition chamber having a negative electric potential relative to the positively charged ion. Some deposition processes maintain the substrate to be coated at the same electric potential as the anode. Other processes use a biasing source to lower the potential of the substrate and thereby make the substrate relatively more attractive to the positively charged ions. In either case, the substrate becomes coated with the vaporized material liberated from the cathode.

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REPLACED SHEETS SG

☒ Description	: paged 1... to paged 13...
☐ Claim(s)	: paged 14... to paged 18...
☒ Drawing(s)	: paged 19... to paged 5/5...
☒ Abstract	: paged 19... to paged 19...

1 Presently available cathodic arc coaters typically use a cooled
2 cathode fixed in place within the coater. One cooling scheme provides
3 a manifold attached to the cathode that permits the passage of coolant
4 between the cathode and manifold. Another scheme uses coolant
5 piping connected to a hollow cathode. A problem with either scheme
6 is that the cathode must be machined to accept the manifold or piping.
7 Not all cathode materials are amenable to machining and even where
8 possible, machining adds significantly to the cost of the consumable
9 cathode. Another problem with the above described "direct cooling"
10 schemes is the labor and time required to replace the cathode when its
11 useful life has expired. In the previous example where a manifold (or
12 piping) is mechanically attached to the cathode, the manifold (or
13 piping) must be detached from the old cathode and attached to a new
14 one, and the deposition chamber subsequently cleaned of coolant. For
15 those applications which require cathode replacement after each coating
16 run, the labor costs and down time can be considerable.

17 Present vapor deposition coaters are typically not well adapted
18 for production environments, where it is desirable to establish a
19 continuous, high-volume stream of parts passing through numerous
20 manufacturing operations. Continuous processing helps minimize
21 downtime between operations and speeds up production rates.
22 Presently available low volume laboratory coaters commonly use the
23 previously mentioned fixed cathode that must be replaced after one or
24 two runs. The effort required to replace the cathode, and the limited
25 volume of laboratory coaters, make laboratory coaters an impractical
26 means of providing a continuous, high-volume stream of coated parts.
27 High-volume batch coaters, on the other hand, are capable of coating
28 large numbers of parts, but do not provide a continuous stream.
29 Specifically, the length of time required to fill a large batch coater
30 from upstream manufacturing operations and the duration of the coating



1 run make large batch coaters ill suited for continuous production
2 environments.

3 In short, what is needed is a vapor deposition production system
4 that operates efficiently, one capable of repeatably providing a high
5 quality coating on a substrate, one capable of providing a continuous,
6 high-volume stream of coated parts, and one that operates cost
7 effectively.

8 DISCLOSURE OF THE INVENTION

9 It is, therefore, an object of the present invention to provide a
10 vapor deposition production system capable of producing a high quality
11 coating on a substrate.

12 It is an object of the present invention to provide a vapor
13 deposition production system capable of providing a continuous high-
14 volume stream of coated substrates.

15 It is an object of the present invention to provide a vapor
16 deposition production system that operates efficiently and cost
17 effectively.

18 According to the present invention, a vapor deposition
19 production system for coating substrates is provided which includes a
20 plurality of vapor deposition coaters, a plurality of platters, a platter
21 docking station, a shuttle track, and means for transporting the platters
22 between the coaters and the platter docking station. The shuttle track
23 connects the platter docking station and the coaters. Platters selectively
24 removed from the coaters are transported along the shuttle track to the
25 platter docking station where processed substrates are unloaded from
26 the platters and unprocessed substrates loaded on to the platters.

27 An advantage of the present invention is that a vapor deposition
28 production system for coating substrates is provided that is capable of
29 producing a continuous high-volume stream of coated substrates. One



1 characteristic that gives the present invention that capability is the
2 cathode utilized in each coater. Specifically, the cathode is not directly
3 connected to a cooling source, requires minimum machining, and is
4 easily installed and removed. Downtime attributable to cathode
5 removal and installation is effectively eliminated. Another
6 characteristic that gives the present invention production system the
7 capability of producing a continuous high-volume stream of coated
8 substrates is the handling system which includes the platters, shuttle
9 track, and platter docking station. These elements, by themselves,
10 minimize the time and labor required to process a large volume of
11 parts. Automation of the coaters, platters, shuttle track, and platter
12 docking station, as is later described, can even further reduce the time
13 and labor required, and facilitate production of a high-volume stream of
14 coated substrates.

15 Another advantage of the present invention is that an efficient,
16 cost effective vapor deposition production system for coating substrates
17 is provided. The characteristics stated above that give the present
18 invention production system the capability of producing a continuous
19 high-volume stream of coated substrates are the same characteristics
20 that make it efficient and cost effective. In addition, the relatively
21 inexpensive form of the consumable cathode (e.g., minimal machining
22 required) minimizes the cost per run, consequently increasing the cost
23 effectiveness of the system.

24 These and other objects, features and advantages of the present
25 invention will become apparent in light of the detailed description of
26 the best mode embodiment thereof, as illustrated in the accompanying
27 drawings.

1 **BRIEF DESCRIPTION OF THE DRAWINGS**

2 FIG.1 is a diagrammatic view of the present invention vapor
3 deposition production system for coating substrates.

4 FIG.2 is a diagrammatic view of one of the plurality of coaters
5 in the present invention vapor deposition production system for coating
6 substrates.

7 FIG.3 is a diagrammatic embodiment of a disk-shaped cathode
8 and contactor of a present invention coater.

9 FIG.4 is a diagrammatic embodiment of an annular-shaped
10 cathode and contactor of a present invention coater.

11 FIG.5 is a diagrammatic top view of a platter.

12 FIG.6 is a sectional view of the platter shown in FIG.5.

13 FIG.7 is a diagrammatic perspective view of the shuttle car,
14 bearing a platter, on a section of shuttle track.

15 **BEST MODE FOR CARRYING OUT THE INVENTION**

16 **I. Apparatus**

17 Referring to FIGS. 1 and 2, a vapor deposition production
18 system 10 for coating substrates 12 includes a plurality of vapor
19 deposition coaters 14, a plurality of platters 16, a platter docking
20 station 18, a shuttle track 20, and means 22 for driving a platter 16
21 between a coater 14 and the platter docking station 18. The vapor
22 deposition coaters 14 are preferably cathodic arc type coaters, although
23 other vapor deposition coaters may be used alternatively. Each
24 cathodic arc coater 14 (see FIG.2) includes a vessel 24, means 30 for
25 maintaining a vacuum in the vessel 24, a contactor 32, an actuator 34
26 for selectively actuating the contactor 32 into electrical contact with the
27 cathode 36, and means 38 for sustaining an arc of electrical energy
28 between the cathode 36 and an anode 39. A coolant supply 40
29 maintains the coater 14 within acceptable temperatures by cycling



1 coolant through cooling passages 44,46 within the vessel 24 and
2 contactor 32. The means 30 for maintaining a vacuum in the vessel 24
3 preferably includes a mechanical rough vacuum pump 50 and a high-
4 volume diffusion-type vacuum pump 52 piped to the interior of the
5 vessel 24. Other vacuum means may be used alternatively. The means
6 38 for sustaining an arc of electrical energy between the cathode 36 and
7 an anode 39 includes a direct current (D.C.) power supply 54. The
8 vessel 24 is preferably electrically connected to act as an anode,
9 although an anode (not shown) may be positioned within the vessel 24.
10 An arc initiator 56, maintained at or near the electrical potential of the
11 anodic vessel 24, is used to initiate an arc.

12 The contactor 32 includes a head 58 attached to a shaft 60, and
13 means 62 for cooling the contactor 32. The head 58 is positioned
14 inside the vessel 24 and the shaft 60 extends from the head 58 to
15 outside the vessel 24. An insulative disk 64 electrically insulates the
16 contactor 32 from the vessel 24. The means 62 for cooling the
17 contactor 32 preferably includes a cooling tube 66 coaxially positioned
18 within the shaft 60, a coolant inlet port 68 connected to the cooling
19 tube 66, and a coolant exit port 70 connected to the passage 46 formed
20 between the coaxial coolant tube 66 and shaft 60. The coaxial
21 arrangement between the cooling tube 66 and the shaft 60 allows
22 coolant to flow in the cooling tube 66 and exit via the passage 46
23 between the shaft 60 and the cooling tube 66, or vice versa. The head
24 58 (see FIGS. 3 and 4) includes a cup 72 and a magnetic field
25 generator 74. The magnetic field generator 74 is disposed within the
26 cup 72 and the cup 72 is fixed to the contactor shaft 60. The magnetic
27 field generator 74 generates a magnetic field that runs parallel to the
28 evaporative surface 88 (described below) of the cathode 36. The
29 actuator 34 (see FIG.2) for selectively actuating the contactor 32 into
30 electrical contact with the cathode 36 includes a pair of two-way

1 actuating cylinders 78 (hydraulic or pneumatic) acting between a shaft
2 flange 80 attached to the contactor shaft 60 and the vessel 24.

3 Mechanical apparatus (not shown) may be used in place of the
4 actuating cylinders 78.

5 Deflector shields 82 are used throughout the coater 14 to
6 confine the vaporized cathode materials in the area of the substrates 12.
7 The deflector shields 82 attached to the vessel 24 , platter 16, and
8 contactor 32 also minimize undesirable material build-up on those
9 surfaces. In the preferred embodiment, the deflector shields 82
10 attached to the vessel 24 are electrically connected to the vessel 24 and
11 are made of an electrically conductive material resistant to corrosion,
12 such as stainless steel.

13 In a first embodiment (FIG.3), the cathode 36 is a cylindrical
14 disk having substantially parallel first 84 and second 86 end surfaces,
15 and an evaporative surface 88 extending therebetween. In a second
16 embodiment (FIG.4), the cathode 36 is an annulus having substantially
17 parallel first 84 and second 86 end surfaces, and an evaporative surface
18 88 and bore 90 extending between the end surfaces 84,86.

19 Referring to FIGS. 1,5, and 6, a platter 16 for holding the
20 cathode 36 and substrates 12 is mounted on rollers 92 for easy insertion
21 and removal from the vessel 24. The platter 16 (see FIGS. 5 and 6)
22 includes a tray 94, a plurality of pedestals 96, a rack gear 98 attached
23 to a side of the platter 16, and means 100 for rotating the pedestals 96.
24 The cathode 36 is mounted in the center of the platter 16 (see FIGS. 3
25 and 4), on top of a spacer 102 and an electrical insulator 104. The
26 means 100 for rotating the pedestals 96 may, for example, include a
27 center gear 106 engaged with a plurality of pedestal gears 108. Each
28 pedestal gear 108 is fixed to a pedestal 96, and the center 106 and
29 pedestal 108 gears are pivotly attached to the tray 94. A gear 110 (see
30 FIG.2) positioned inside the vessel 24 engages the center gear 106



1 when the platter 16 is positioned inside the vessel 24. A shaft 112
2 extending through the vessel wall connects the gear 110 to a drive unit
3 (D1), which provides the power means for rotating the substrates 12.
4 A second gear 114 and drive unit (D2) provide a similar function for
5 moving the platter 16 in and out of the vessel 24. The second gear
6 114, positioned inside the vessel 24, engages the rack gear 98 attached
7 to the platter 16. A shaft 116 extending through the vessel wall
8 connects the second gear 114 to the second drive unit (D2).

9 Each coater 14 preferably includes a biasing source 118 for
10 electrically biasing the substrates 12. A contact 120, which makes
11 electrical connection with the platter 16, electrically connects the
12 biasing source 118 to the substrates 12 when the platter 16 is installed
13 in the vessel 24. Other means for electrically connecting the substrates
14 12 to the biasing source 118 may be used alternatively.

15 Referring to FIG.7, the preferred means 22 for driving a platter
16 16 between a coater 14 and the platter docking station 18 is a shuttle
17 car 122. The shuttle car 122 includes a pair of tracks 124 for receiving
18 the rollers 92 of a platter 16, a set of rollers 125 for travel along the
19 shuttle track 20, a third drive unit (D3) for driving the shuttle car 122
20 along the shuttle track 20, and a fourth drive unit (D4) for loading a
21 platter 16 onto, and off of, the shuttle car 122. The third drive unit
22 (D3) may, for example, be connected to a gear 126 engaged with a
23 rack gear 128 attached to the shuttle track 20.

24 Referring to FIG.1, the platter docking station 18 includes a
25 first 130 and a second 132 dock. Each dock 130,132 includes means
26 134 for loading and unloading a platter 16 into and out of the dock
27 130,132, respectively. For example, the means 134 for loading and
28 unloading a platter 16 from the dock 130,132 may include a gear 136
29 engagable with the rack gear 98 of each platter 16, driven by a fifth
30 drive unit (D5) attached to each dock 130,132. The means 134 for



1 loading and unloading a platter 16 from the dock 130,132 further
2 includes a pair of tracks 138 to support the rollers 92 of each platter
3 16.

4 Each drive unit (D1-D5), includes a commercially available
5 "drive" which comprises an electric motor coupled with a gear box
6 (not shown). A commercially available position indicator (not shown),
7 such as a shaft-type or a linear-type encoder, is used to indicate relative
8 position. For example, a shaft-type encoder connected to the third
9 drive unit (D3) can be used to determine shuttle car 122 position by
10 equating third drive unit (D3) shaft rotations to linear distance from a
11 known reference point. Alternatively, shuttle car 122 (or platter 16)
12 position could be determined by other means such as limit switches,
13 etc.

14 A controller 140 having a central processing unit, an input
15 device, an output device, and a memory storage device is used to
16 control each of the coaters 14 and the shuttle car 122, shuttling platters
17 16 between the coaters 14 and the platter docking station 18. A wide
18 variety of controllers 140 are commercially available. Accordingly, the
19 details of the controller 140 shall be omitted here in favor of the
20 functional requirements of the controller.

21 II. Operation of the Apparatus

22 Referring to FIG.1, in the operation of the present invention
23 vapor deposition production system 10 for coating substrates 12, an
24 empty platter 16 is positioned in the first dock 130 of the platter
25 docking station 18. An operator (not shown) loads a cathode 36 and
26 substrates 12 to be coated onto the empty platter 16. At the same time,
27 a second platter 16 loaded with coated substrates 12 is cooling in the
28 second dock 132 of the platter docking station 18. At this point in
29 time, one of the coaters 14 is empty, waiting to receive a platter 16



1 bearing substrates 12 to be coated. After the first platter 16 is loaded
2 with a cathode 36 and substrates 12, the first platter 16 is removed
3 from the first dock 130 and loaded onto the shuttle car 122. The
4 shuttle car 122 transports the loaded platter 16 to the empty coater 14
5 and the platter 16 is subsequently inserted into the coater 14.

6 Referring to FIG.2, when the platter 16 is inserted into the
7 coater 14, the actuating cylinders 78 actuate the contactor 32 into
8 contact (physical and electrical) with the cathode 36 and the vessel 24
9 is closed. The mechanical rough vacuum pump 50 is subsequently
10 operated to evacuate the vessel to a predetermined pressure. Once that
11 pressure is reached, the high-volume diffusion vacuum pump 52 is
12 operated to further evacuate the vessel 24 to near vacuum conditions.
13 The substrates 12 are then cleaned of any remaining contaminants
14 and/or oxidation by a method such as "sputter cleaning". Sputter
15 cleaning is a process well known in the art and will not be described in
16 detail here. Other cleaning methods may be used alternatively. While
17 the substrates 12 are cleaned, the contaminants are purged typically
18 using an inert gas.

19 Prior to initiating an arc several steps are completed, including:
20 (1) the biasing source 118 is activated and the substrates 12 are
21 electrically biased; (2) the substrates 12 are placed in motion at a
22 particular rotational speed; (3) the power supply 54 is set to establish
23 an arc having a particular magnitude of current and voltage, but no arc
24 is initiated; (4) the vacuum pumps 50,52 establish and maintain a
25 particular vacuum pressure of gas within the vessel 24; and (5) coolant
26 flows are established through the vessel cooling passages 44 and the
27 contactor cooling passages 46. Specific process parameters will depend
28 upon factors such as the substrate 12 material, the material to be
29 coated, and the desired characteristics of the coating, etc.



1 Once the aforementioned steps have been completed, the arc
2 initiator 56 causes an arc to jump between the cathode 36 and the
3 deflector shields 82 electrically connected to the anodic vessel 24. The
4 magnetic field generator 74 subsequently drives the arc along an arc
5 path 142 (see FIG.3) around the evaporative surface 88 of the cathode
6 36. The energy delivered by the arc causes the material at the cathode
7 spot to vaporize, thereby liberating atoms, molecules, ions, electrons,
8 and particles from the cathode 36. FIG.3 shows an eroded cathode 36
9 in phantom. The erosion is substantially symmetrical relative to the arc
10 path 142. The biased substrates 12 attract the ions, causing them to
11 accelerate toward the substrates 12, attach and collectively form a
12 coating of the cathode material. Rotation of the substrates 12 relative
13 to the cathode 36 promotes uniform deposition of the coating on the
14 substrate 12. Coolant passing through the contactor 32 directly cools
15 the contactor 32, and indirectly cools the cathode 36. When a coating
16 of sufficient thickness has been deposited on the substrates 12, the
17 power supply 54 is turned off and the arc extinguished. The vessel 24
18 is purged with inert gas and brought to ambient pressure. The
19 contactor 32 is actuated out of contact with the cathode 36, the vessel
20 24 opened, and the platter 16 is removed from the vessel 24 and placed
21 onto the shuttle car 122.

22 Referring to FIG.1, during the coating run, the empty shuttle
23 car 122 returns to the platter docking station 18 and the second platter
24 16 is transported across the shuttle car 122 to the first dock 130. The
25 shuttle car 122 then travels to the next coater 14 to be emptied,
26 receives the platter 16 bearing coated substrates 12 and transports the
27 platter 16 to the platter docking station 18, where the platter 16 is
28 transferred to the second dock 132. Thus, the cycle of coating
29 substrates 12 repeats itself.



1 The controller 140 provides the command logic for coordinating
2 the tasks of transporting platters 16 along the shuttle track 20, and
3 within the platter docking station 18. For example, the operator (not
4 shown) enters a command to transport the shuttle car 122 bearing a
5 platter 16 from a particular coater 14 to the platter docking station 18.
6 The controller 140 compares the actual position of the loaded shuttle
7 car 122 with the stored reference value of the platter docking station 18
8 and commands the third drive unit (D3) to transport the shuttle car 122
9 to the platter docking station 18. A real time signal from the position
10 indicator sensing the actual position of the shuttle car 122 is sent to the
11 controller 140 until, the actual position signal coincides with the
12 reference value associated with the platter docking station 18. Similar
13 control logic is used to move the platters 16 in and out of the first 130
14 and second 132 docks and in and out of the coaters 14.

15 The controller 140 also provides the command logic for
16 operating each coater 14. The described steps of: (1) opening the
17 vessel 24; (2) actuating the contactor 32 into electrical contact with the
18 cathode 36; (3) operating the vacuum pumps 50,52 to evacuate the
19 coater 14; (4) biasing the substrates 12 via the biasing source 118; (5)
20 rotating the substrates 12 by driving the gears 106,108 attached to the
21 platter 16; (6) creating a potential difference between the cathode 36
22 and the anodic vessel 24 via the power supply 54; and (7) initiating an
23 arc between the cathode 36 and the deflector shields 82 (or vessel 24);
24 are all coordinated by commands stored within the controller 140. The
25 commands can be created and stored in the form of a software program
26 using a commercially available computer software programming
27 language.

28 Although this invention has been shown and described with
29 respect to the detailed embodiments thereof, it will be understood by
30 those skilled in the art that various changes in form and detail thereof



1 may be made without departing from the spirit and the scope of the
2 invention. For example, the described platter docking station 18 is a
3 simplistic version capable of satisfying the present invention production
4 system 10. More complex systems capable of handling more than two
5 platters 16, such as a turret, may be used alternatively. Another
6 change from the best mode may be found in the drive units. For
7 example, a linear motor could be used to drive the shuttle car and
8 hydraulic actuators could be used to move a platter 16 on and off the
9 shuttle car 122.





We claim:

- 1 1. A vapor deposition production system for coating substrates,
2 comprising:
3 a plurality of vapor deposition coaters;
4 a plurality of platters;
5 a platter docking station;
6 a shuttle track, connecting said docking station and said coaters;
7 means for transporting said platters between said coaters and
8 said docking station;
9 wherein said platters are selectively transported between said
10 coaters and said docking station via said shuttle track, and into, and out
11 of, said coaters.

- 1 2. A vapor deposition production system according to claim 1,
2 further comprising:
3 a controller, having a central processing unit, connected to said
4 coaters and said means for transporting said platters, wherein said
5 controller controls the operation of said coaters and the operation of
6 said means for transporting said platters.

- 1 3. A vapor deposition production system according to claim 2,
2 wherein said means for transporting said platters between said coaters
3 and said docking station, comprises:
4 a shuttle car, adapted for travel along said shuttle track, having
5 a drive means for propelling said shuttle car.

- 1 4. A vapor deposition production system according to claim 3,
2 wherein each said coater comprises:
3 a vessel;
4 means for maintaining a vacuum in said vessel;





5 a cathode, mounted on one of said platters;
6 a contactor, positioned inside said vessel;
7 means for selectively sustaining an arc of electrical energy
8 between said cathode and an anode, wherein said means for selectively
9 sustaining an arc of electrical energy is electrically connected to said
10 contactor; and
11 an actuator, wherein said actuator selectively actuates said
12 contactor into contact with said cathode, and thereby electrically
13 connects said cathode to said means for sustaining an arc of electrical
14 energy;
15 wherein said controller controls operation of said means for
16 maintaining a vacuum in said vessel, and said means for selectively
17 sustaining an arc of electrical energy, and said actuator.

1 5. A vapor deposition production system according to claim 4,
2 wherein said cathode is disk-shaped having a pair of end surfaces
3 connected by an evaporative surface;
4 wherein said actuator actuates said contactor into contact with
5 one of said end surfaces of said cathode, thereby electrically connecting
6 said cathode to said means for selectively sustaining an arc of electrical
7 energy.

1 6. A vapor deposition production system according to claim 5,
2 wherein said coater further comprises means for driving said arc around
3 said evaporative surface, wherein said means for driving said arc is
4 positioned in close proximity to said cathode, and said means for
5 driving said arc produces a magnetic field that permeates said cathode.

1 7. A vapor deposition production system according to claim 4,
2 wherein said cathode is annular-shaped having a pair of end surfaces,





3 and an evaporative surface and a bore extending between said end
4 surfaces;
5 wherein said actuator actuates said contactor into electrical
6 contact with said cathode, thereby electrically connecting said cathode
7 to said means for selectively sustaining an arc of electrical energy.

1 8. A vapor deposition production system according to claim 7,
2 wherein said coater further comprises means for driving said arc around
3 said evaporative surface, wherein said means for driving said arc is
4 positioned within said bore of said cathode, and said means for driving
5 said arc produces a magnetic field that permeates said cathode.

1 9. A vapor deposition production system according to claim 4,
2 wherein said contactor comprises:
3 a head, positioned inside said vessel;
4 a shaft, attached to said head, extending from said head to
5 outside said vessel.

1 10. A vapor deposition production system according to claim 9,
2 wherein said platter further comprises selectively rotatable pedestals,
3 for supporting the substrates.

1 11. A vapor deposition production system according to claim 10,
2 further comprising:
3 a biasing source, for electrically biasing the substrates attached
4 to said platters positioned within said coaters;
5 means for electrically connecting said biasing source to the
6 substrates.





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1 12. A vapor deposition production system according to claim 11,
2 wherein said means for electrically connecting said biasing source to
3 the substrates electrically connects said biasing source to said platter,
4 and said platter is electrically connected to the substrates.

1 13. A vapor deposition production system according to claim 12,
2 wherein said cathode is disk-shaped having a pair of end surfaces
3 connected by an evaporative surface;
4 wherein said actuator actuates said contactor into contact with
5 one of said end surfaces of said cathode, thereby electrically connecting
6 said cathode to said means for selectively sustaining an arc of electrical
7 energy.

1 14. A vapor deposition production system according to claim 13,
2 wherein said coater further comprises means for driving said arc around
3 said evaporative surface, wherein said means for driving said arc is
4 positioned in close proximity to said cathode, and said means for
5 driving said arc produces a magnetic field that permeates said cathode.

1 15. A vapor deposition production system according to claim 12,
2 wherein said cathode is annular-shaped having a pair of end surfaces,
3 and an evaporative surface and a bore extending between said end
4 surfaces;
5 wherein said actuator actuates said contactor into electrical
6 contact with said cathode, thereby electrically connecting said cathode
7 to said means for selectively sustaining an arc of electrical energy.

1 16. A vapor deposition production system according to claim 15,
2 wherein said coater further comprises means for driving said arc around
3 said evaporative surface, wherein said means for driving said arc is





- 4 positioned within said bore of said cathode, and said means for driving
5 said arc produces a magnetic field that permeates said cathode.



ABSTRACT OF THE DISCLOSURE

A vapor deposition production system for coating substrates is provided which includes a plurality of vapor deposition coaters, a plurality of platters, a platter docking station, a shuttle track, and apparatus for transporting the platters between the coaters and the platter docking station. The shuttle track connects the platter docking station and the coaters. Platters selectively removed from the coaters are transported along the shuttle track to the platter docking station where processed substrates are unloaded from the platters and unprocessed substrates loaded on to the platters.

FIG. 1

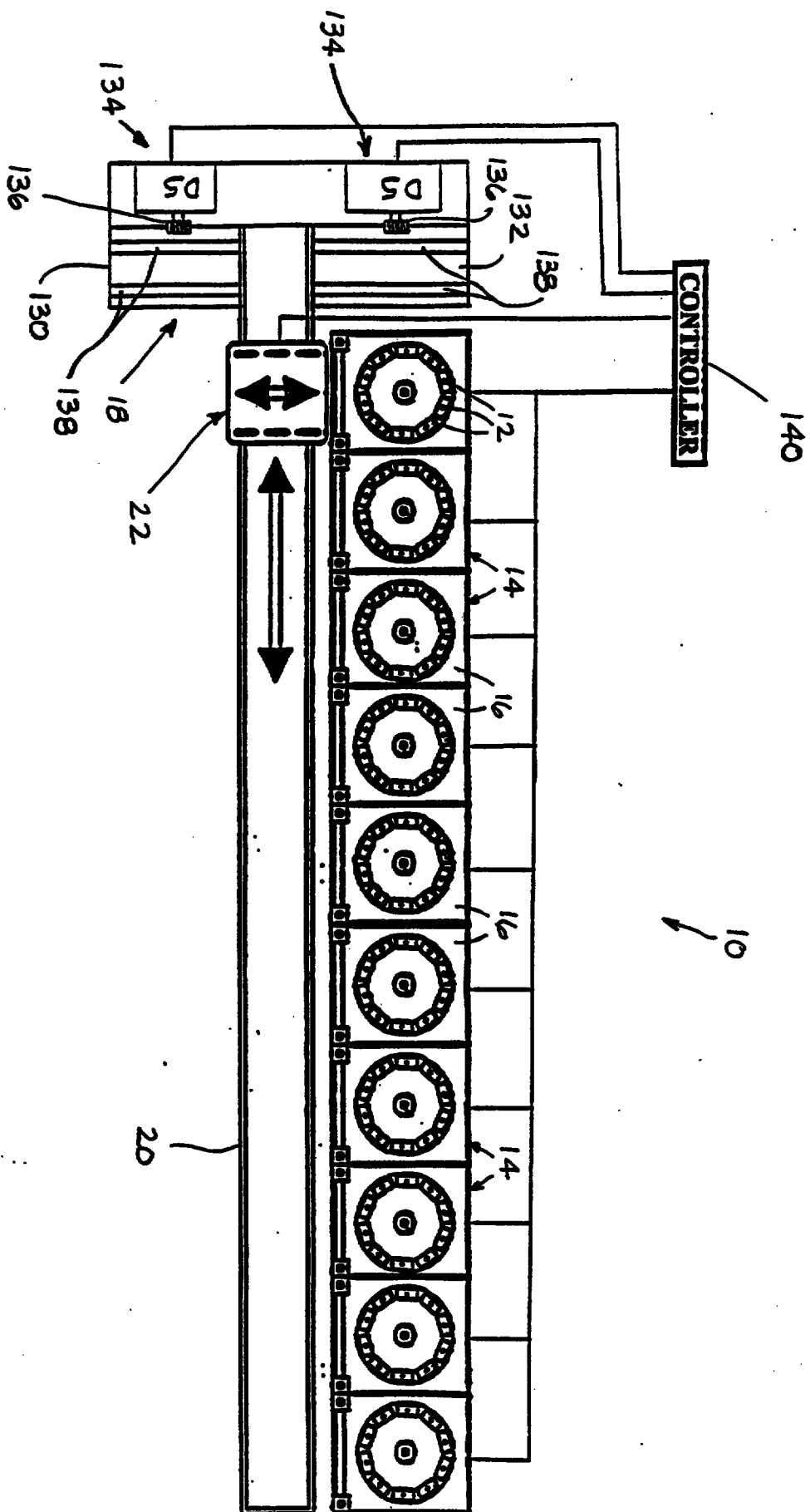


FIG. 2

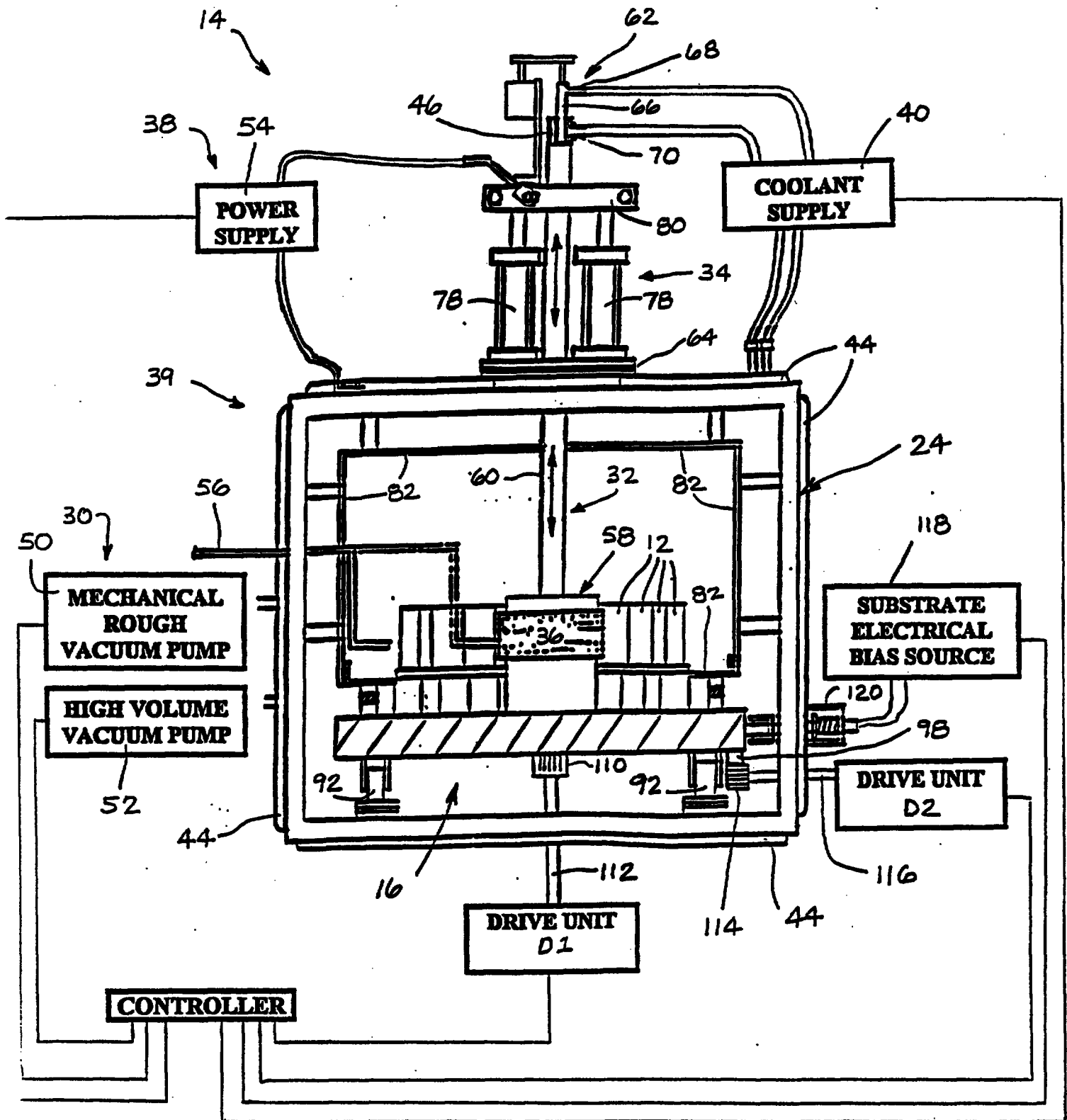


FIG. 3

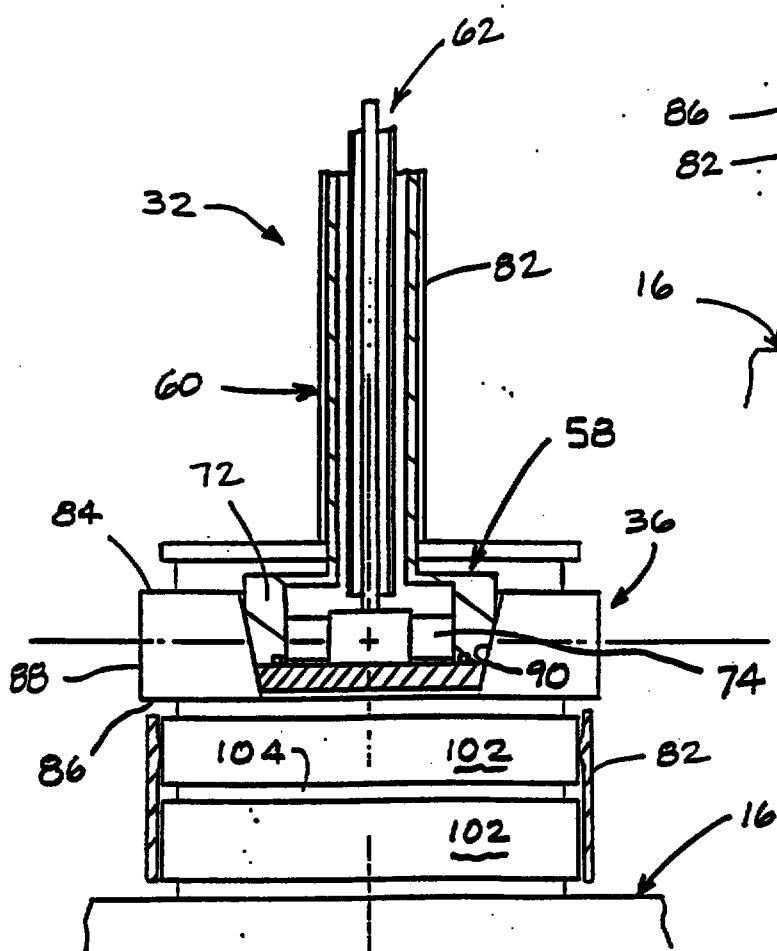
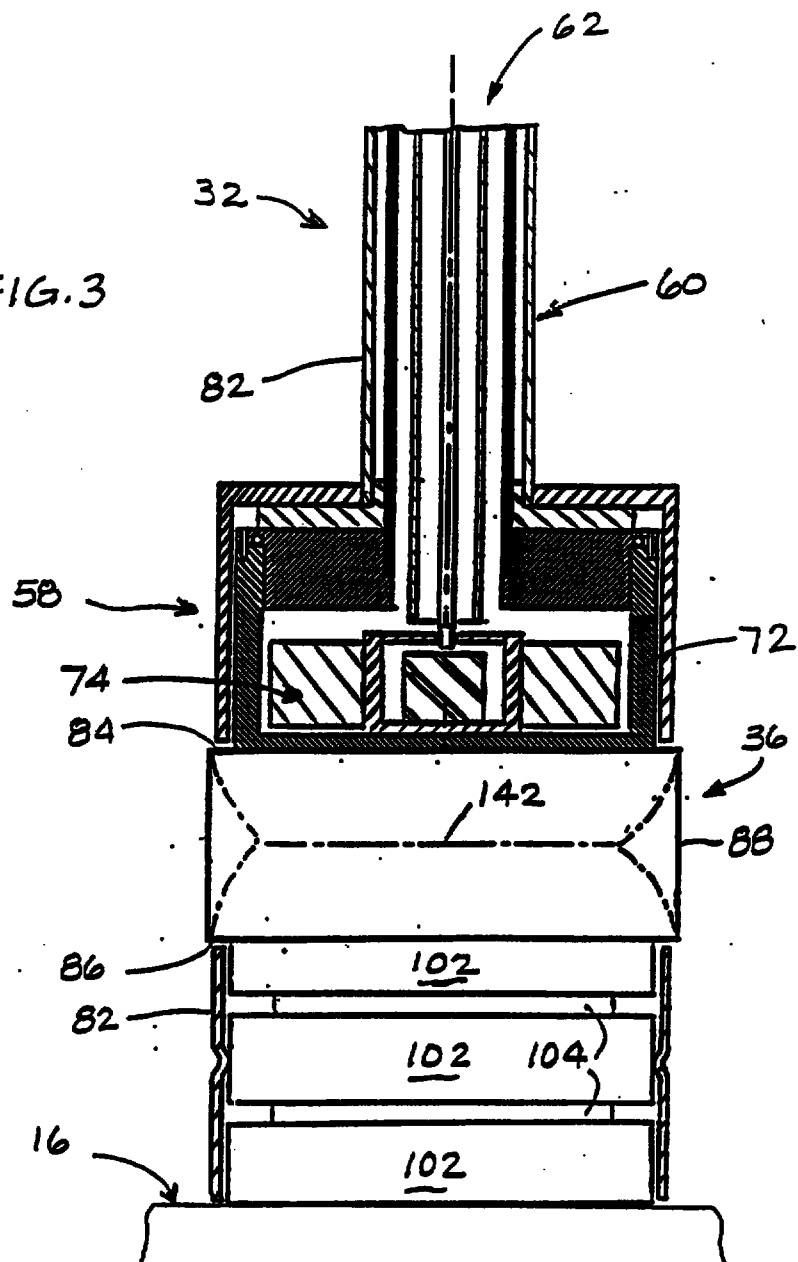


FIG. 4

FIG. 5

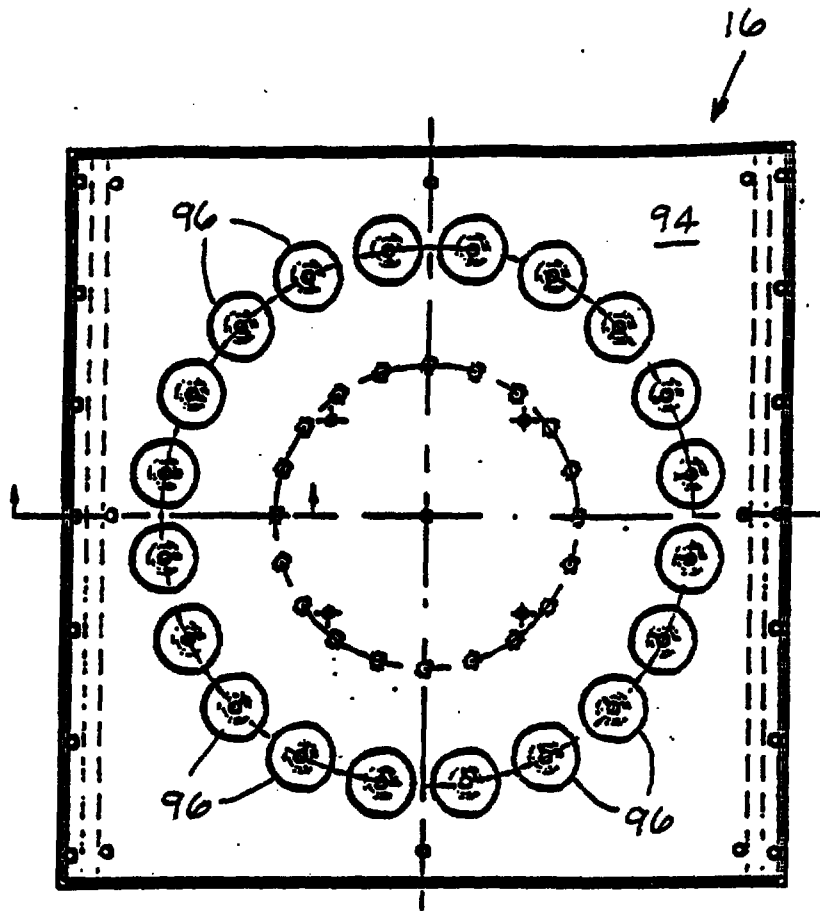


FIG. 6

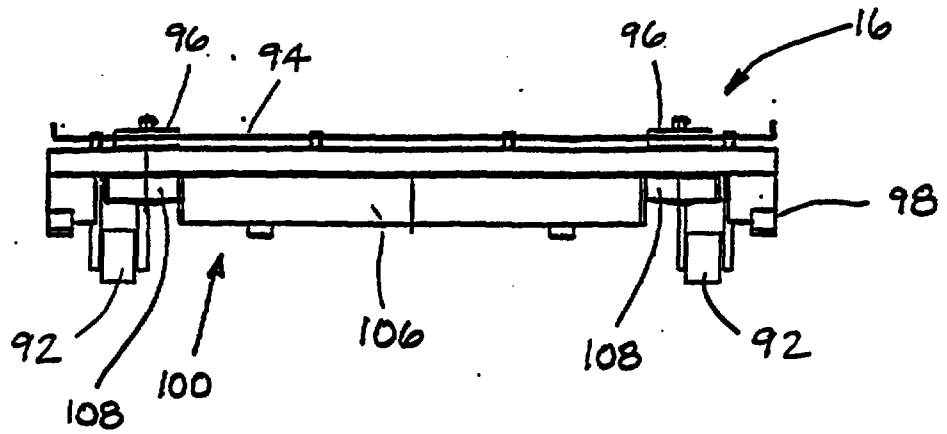
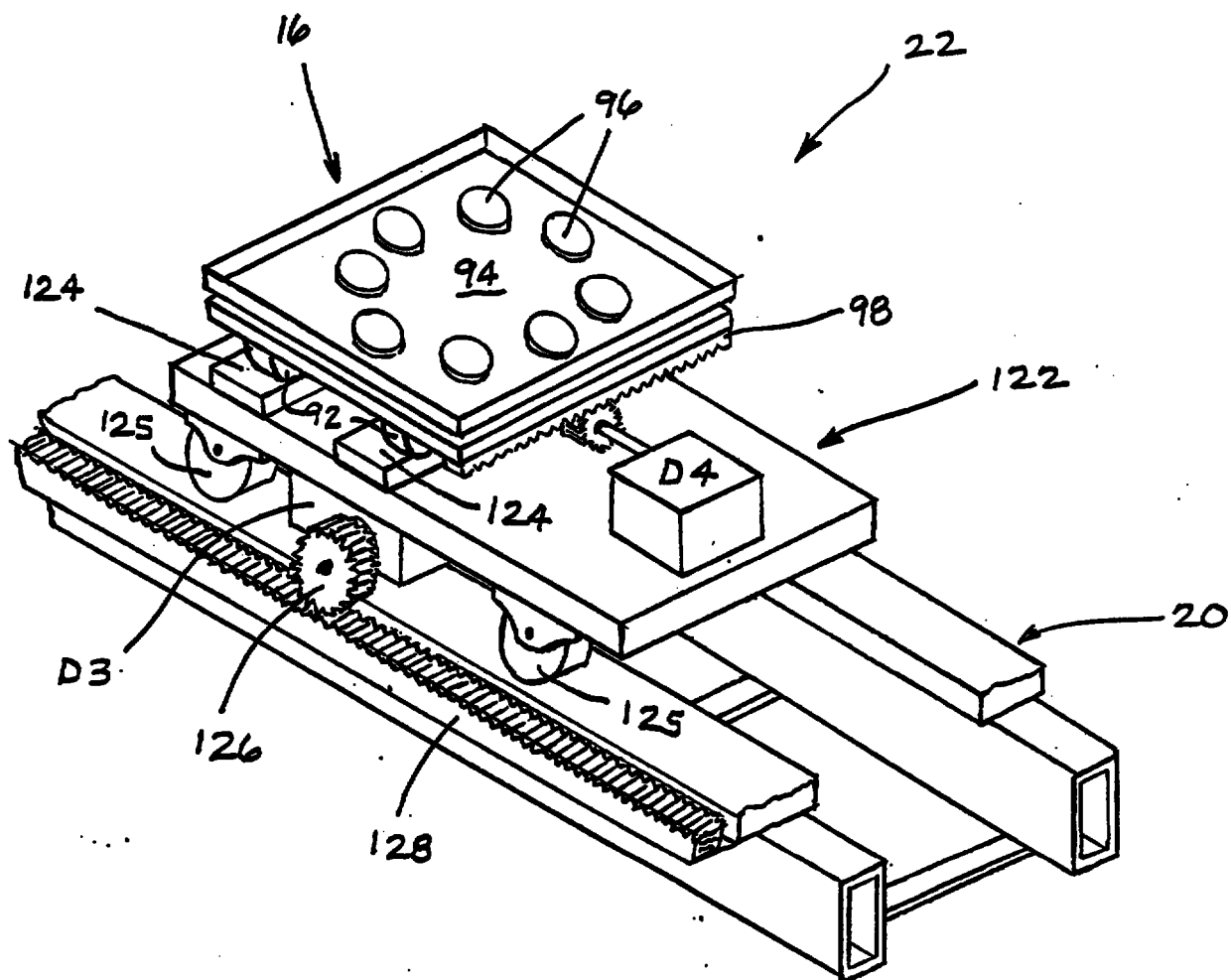


FIG. 7



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☒ Description : paged 1 to paged 13
☒ Claim(s) : paged 14 to paged 18
☒ Drawing(s) : paged 15 to paged 515
☒ Abstract : paged 19 to paged 19

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Vapor Deposition Production Coating System

BACKGROUND OF THE INVENTION

1. Technical Field

This invention relates to vapor deposition apparatus in general, and to production systems in particular.

2. Background Information

Vapor deposition as a means for applying a coating to a substrate is a known art that includes processes such as chemical vapor deposition, physical vapor deposition, and cathodic arc vapor deposition. Chemical vapor deposition involves introducing reactive gaseous elements into a deposition chamber containing one or more substrates to be coated. Physical vapor deposition involves providing a source material and a substrate to be coated in a evacuated deposition chamber. The source material is converted into vapor by an energy input, such as heating by resistive, inductive, or electron beam means. Cathodic arc vapor deposition involves a source material and a substrate to be coated placed in an evacuated deposition chamber containing only a relatively small amount of gas. An arc, traveling between the cathode and an anode, vaporizes the cathode into a plasma containing atoms, molecules, ions, electrons, and particles. Positively charged ions liberated from the cathode are attracted toward any object within the deposition chamber having a negative electric potential relative to the positively charged ion. Some deposition processes maintain the substrate to be coated at the same electric potential as the anode. Other processes use a biasing source to lower the potential of the substrate and thereby make the substrate relatively more attractive to the positively charged ions. In either case, the substrate becomes coated with the vaporized material liberated from the cathode.

This is the replacement sheet

Date: 30 NOV 1998

1 Presently available cathodic arc coaters typically use a cooled
2 cathode fixed in place within the coater. One cooling scheme provides
3 a manifold attached to the cathode that permits the passage of coolant
4 between the cathode and manifold. Another scheme uses coolant
5 piping connected to a hollow cathode. A problem with either scheme
6 is that the cathode must be machined to accept the manifold or piping.
7 Not all cathode materials are amenable to machining and even where
8 possible, machining adds significantly to the cost of the consumable
9 cathode. Another problem with the above described "direct cooling"
10 schemes is the labor and time required to replace the cathode when its
11 useful life has expired. In the previous example where a manifold (or
12 piping) is mechanically attached to the cathode, the manifold (or
13 piping) must be detached from the old cathode and attached to a new
14 one, and the deposition chamber subsequently cleaned of coolant. For
15 those applications which require cathode replacement after each coating
16 run, the labor costs and down time can be considerable.

17 Present vapor deposition coaters are typically not well adapted
18 for production environments, where it is desirable to establish a
19 continuous, high-volume stream of parts passing through numerous
20 manufacturing operations. Continuous processing helps minimize
21 downtime between operations and speeds up production rates.
22 Presently available low volume laboratory coaters commonly use the
23 previously mentioned fixed cathode that must be replaced after one or
24 two runs. The effort required to replace the cathode, and the limited
25 volume of laboratory coaters, make laboratory coaters an impractical
26 means of providing a continuous, high-volume stream of coated parts.
27 High-volume batch coaters, on the other hand, are capable of coating
28 large numbers of parts, but do not provide a continuous stream.
29 Specifically, the length of time required to fill a large batch coater
30 from upstream manufacturing operations and the duration of the coating

1 run make large batch coaters ill suited for continuous production
2 environments.

3 In short, what is needed is a vapor deposition production system
4 that operates efficiently, one capable of repeatably providing a high
5 quality coating on a substrate, one capable of providing a continuous,
6 high-volume stream of coated parts, and one that operates cost
7 effectively.

8 DISCLOSURE OF THE INVENTION

9 It is, therefore, an object of the present invention to provide a
10 vapor deposition production system capable of producing a high quality
11 coating on a substrate.

12 It is an object of the present invention to provide a vapor
13 deposition production system capable of providing a continuous high-
14 volume stream of coated substrates.

15 It is an object of the present invention to provide a vapor
16 deposition production system that operates efficiently and cost
17 effectively.

18 According to the present invention, a vapor deposition
19 production system for coating substrates is provided which includes a
20 plurality of vapor deposition coaters, a plurality of platters, a platter
21 docking station, a shuttle track, and means for transporting the platters
22 between the coaters and the platter docking station. The shuttle track
23 connects the platter docking station and the coaters. Platters selectively
24 removed from the coaters are transported along the shuttle track to the
25 platter docking station where processed substrates are unloaded from
26 the platters and unprocessed substrates loaded on to the platters.

27 An advantage of the present invention is that a vapor deposition
28 production system for coating substrates is provided that is capable of
29 producing a continuous high-volume stream of coated substrates. One

1 characteristic that gives the present invention that capability is the
2 cathode utilized in each coater. Specifically, the cathode is not directly
3 connected to a cooling source, requires minimum machining, and is
4 easily installed and removed. Downtime attributable to cathode
5 removal and installation is effectively eliminated. Another
6 characteristic that gives the present invention production system the
7 capability of producing a continuous high-volume stream of coated
8 substrates is the handling system which includes the platters, shuttle
9 track, and platter docking station. These elements, by themselves,
10 minimize the time and labor required to process a large volume of
11 parts. Automation of the coaters, platters, shuttle track, and platter
12 docking station, as is later described, can even further reduce the time
13 and labor required, and facilitate production of a high-volume stream of
14 coated substrates.

15 Another advantage of the present invention is that an efficient,
16 cost effective vapor deposition production system for coating substrates
17 is provided. The characteristics stated above that give the present
18 invention production system the capability of producing a continuous
19 high-volume stream of coated substrates are the same characteristics
20 that make it efficient and cost effective. In addition, the relatively
21 inexpensive form of the consumable cathode (e.g., minimal machining
22 required) minimizes the cost per run, consequently increasing the cost
23 effectiveness of the system.

24 These and other objects, features and advantages of the present
25 invention will become apparent in light of the detailed description of
26 the best mode embodiment thereof, as illustrated in the accompanying
27 drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG.1 is a diagrammatic view of the present invention vapor deposition production system for coating substrates.

FIG.2 is a diagrammatic view of one of the plurality of coaters in the present invention vapor deposition production system for coating substrates.

FIG.3 is a diagrammatic embodiment of a disk-shaped cathode and contactor of a present invention coater.

FIG.4 is a diagrammatic embodiment of an annular-shaped cathode and contactor of a present invention coater.

FIG.5 is a diagrammatic top view of a platter.

FIG.6 is a sectional view of the platter shown in FIG.5.

FIG.7 is a diagrammatic perspective view of the shuttle car, bearing a platter, on a section of shuttle track.

BEST MODE FOR CARRYING OUT THE INVENTION

I. Apparatus

Referring to FIGS. 1 and 2, a vapor deposition production system 10 for coating substrates 12 includes a plurality of vapor deposition coaters 14, a plurality of platters 16, a platter docking station 18, a shuttle track 20, and means 22 for driving a platter 16 between a coater 14 and the platter docking station 18. The vapor deposition coaters 14 are preferably cathodic arc type coaters, although other vapor deposition coaters may be used alternatively. Each cathodic arc coater 14 (see FIG.2) includes a vessel 24, means 30 for maintaining a vacuum in the vessel 24, a contactor 32, an actuator 34 for selectively actuating the contactor 32 into electrical contact with the cathode 36, and means 38 for sustaining an arc of electrical energy between the cathode 36 and an anode 39. A coolant supply 40 maintains the coater 14 within acceptable temperatures by cycling

This is the replacement sheet

30 NOV 1998

Date:

1 coolant through cooling passages 44,46 within the vessel 24 and
2 contactor 32. The means 30 for maintaining a vacuum in the vessel 24
3 preferably includes a mechanical rough vacuum pump 50 and a high-
4 volume diffusion-type vacuum pump 52 piped to the interior of the
5 vessel 24. Other vacuum means may be used alternatively. The means
6 38 for sustaining an arc of electrical energy between the cathode 36 and
7 an anode 39 includes a direct current (D.C.) power supply 54. The
8 vessel 24 is preferably electrically connected to act as an anode,
9 although an anode (not shown) may be positioned within the vessel 24.
10 An arc initiator 56, maintained at or near the electrical potential of the
11 anodic vessel 24, is used to initiate an arc.

12 The contactor 32 includes a head 58 attached to a shaft 60, and
13 means 62 for cooling the contactor 32. The head 58 is positioned
14 inside the vessel 24 and the shaft 60 extends from the head 58 to
15 outside the vessel 24. An insulative disk 64 electrically insulates the
16 contactor 32 from the vessel 24. The means 62 for cooling the
17 contactor 32 preferably includes a cooling tube 66 coaxially positioned
18 within the shaft 60, a coolant inlet port 68 connected to the cooling
19 tube 66, and a coolant exit port 70 connected to the passage 46 formed
20 between the coaxial coolant tube 66 and shaft 60. The coaxial
21 arrangement between the cooling tube 66 and the shaft 60 allows
22 coolant to flow in the cooling tube 66 and exit via the passage 46
23 between the shaft 60 and the cooling tube 66, or vice versa. The head
24 58 (see FIGS. 3 and 4) includes a cup 72 and a magnetic field
25 generator 74. The magnetic field generator 74 is disposed within the
26 cup 72 and the cup 72 is fixed to the contactor shaft 60. The magnetic
27 field generator 74 generates a magnetic field that runs parallel to the
28 evaporative surface 88 (described below) of the cathode 36. The
29 actuator 34 (see FIG.2) for selectively actuating the contactor 32 into
30 electrical contact with the cathode 36 includes a pair of two-way

This is the replacement sheet

Date: 30 NOV 1998

1 actuating cylinders 78 (hydraulic or pneumatic) acting between a shaft
2 flange 80 attached to the contactor shaft 60 and the vessel 24.
3 Mechanical apparatus (not shown) may be used in place of the
4 actuating cylinders 78.

5 Deflector shields 82 are used throughout the coater 14 to
6 confine the vaporized cathode materials in the area of the substrates 12.
7 The deflector shields 82 attached to the vessel 24 , platter 16, and
8 contactor 32 also minimize undesirable material build-up on those
9 surfaces. In the preferred embodiment, the deflector shields 82
10 attached to the vessel 24 are electrically connected to the vessel 24 and
11 are made of an electrically conductive material resistant to corrosion,
12 such as stainless steel.

13 In a first embodiment (FIG.3), the cathode 36 is a cylindrical
14 disk having substantially parallel first 84 and second 86 end surfaces,
15 and an evaporative surface 88 extending therebetween. In a second
16 embodiment (FIG.4), the cathode 36 is an annulus having substantially
17 parallel first 84 and second 86 end surfaces, and an evaporative surface
18 88 and bore 90 extending between the end surfaces 84,86.

19 Referring to FIGS. 1,5, and 6, a platter 16 for holding the
20 cathode 36 and substrates 12 is mounted on rollers 92 for easy insertion
21 and removal from the vessel 24. The platter 16 (see FIGS. 5 and 6)
22 includes a tray 94, a plurality of pedestals 96, a rack gear 98 attached
23 to a side of the platter 16, and means 100 for rotating the pedestals 96.
24 The cathode 36 is mounted in the center of the platter 16 (see FIGS. 3
25 and 4), on top of a spacer 102 and an electrical insulator 104. The
26 means 100 for rotating the pedestals 96 may, for example, include a
27 center gear 106 engaged with a plurality of pedestal gears 108. Each
28 pedestal gear 108 is fixed to a pedestal 96, and the center 106 and
29 pedestal 108 gears are pivotly attached to the tray 94. A gear 110 (see
30 FIG.2) positioned inside the vessel 24 engages the center gear 106

This is the replacement sheet

Date: 30 NOV 1998

1 when the platter 16 is positioned inside the vessel 24. A shaft 112
2 extending through the vessel wall connects the gear 110 to a drive unit
3 (D1), which provides the power means for rotating the substrates 12.
4 A second gear 114 and drive unit (D2) provide a similar function for
5 moving the platter 16 in and out of the vessel 24. The second gear
6 114, positioned inside the vessel 24, engages the rack gear 98 attached
7 to the platter 16. A shaft 116 extending through the vessel wall
8 connects the second gear 114 to the second drive unit (D2).

9 Each coater 14 preferably includes a biasing source 118 for
10 electrically biasing the substrates 12. A contact 120, which makes
11 electrical connection with the platter 16, electrically connects the
12 biasing source 118 to the substrates 12 when the platter 16 is installed
13 in the vessel 24. Other means for electrically connecting the substrates
14 12 to the biasing source 118 may be used alternatively.

15 Referring to FIG.7, the preferred means 22 for driving a platter
16 16 between a coater 14 and the platter docking station 18 is a shuttle
17 car 122. The shuttle car 122 includes a pair of tracks 124 for receiving
18 the rollers 92 of a platter 16, a set of rollers 125 for travel along the
19 shuttle track 20, a third drive unit (D3) for driving the shuttle car 122
20 along the shuttle track 20, and a fourth drive unit (D4) for loading a
21 platter 16 onto, and off of, the shuttle car 122. The third drive unit
22 (D3) may, for example, be connected to a gear 126 engaged with a
23 rack gear 128 attached to the shuttle track 20.

24 Referring to FIG.1, the platter docking station 18 includes a
25 first 130 and a second 132 dock. Each dock 130,132 includes means
26 134 for loading and unloading a platter 16 into and out of the dock
27 130,132, respectively. For example, the means 134 for loading and
28 unloading a platter 16 from the dock 130,132 may include a gear 136
29 engagable with the rack gear 98 of each platter 16, driven by a fifth
30 drive unit (D5) attached to each dock 130,132. The means 134 for

This is the replacement sheet

Date: 30 NOV 1998

1 loading and unloading a platter 16 from the dock 130,132 further
2 includes a pair of tracks 138 to support the rollers 92 of each platter
3 16.

4 Each drive unit (D1-D5), includes a commercially available
5 "drive" which comprises an electric motor coupled with a gear box
6 (not shown). A commercially available position indicator (not shown),
7 such as a shaft-type or a linear-type encoder, is used to indicate relative
8 position. For example, a shaft-type encoder connected to the third
9 drive unit (D3) can be used to determine shuttle car 122 position by
10 equating third drive unit (D3) shaft rotations to linear distance from a
11 known reference point. Alternatively, shuttle car 122 (or platter 16)
12 position could be determined by other means such as limit switches,
13 etc.

14 A controller 140 having a central processing unit, an input
15 device, an output device, and a memory storage device is used to
16 control each of the coaters 14 and the shuttle car 122, shuttling platters
17 16 between the coaters 14 and the platter docking station 18. A wide
18 variety of controllers 140 are commercially available. Accordingly, the
19 details of the controller 140 shall be omitted here in favor of the
20 functional requirements of the controller.

21 II. Operation of the Apparatus

22 Referring to FIG.1, in the operation of the present invention
23 vapor deposition production system 10 for coating substrates 12, an
24 empty platter 16 is positioned in the first dock 130 of the platter
25 docking station 18. An operator (not shown) loads a cathode 36 and
26 substrates 12 to be coated onto the empty platter 16. At the same time,
27 a second platter 16 loaded with coated substrates 12 is cooling in the
28 second dock 132 of the platter docking station 18. At this point in
29 time, one of the coaters 14 is empty, waiting to receive a platter 16

This is the replacement sheet

Date: 30 NOV 1998

1 bearing substrates 12 to be coated. After the first platter 16 is loaded
2 with a cathode 36 and substrates 12, the first platter 16 is removed
3 from the first dock 130 and loaded onto the shuttle car 122. The
4 shuttle car 122 transports the loaded platter 16 to the empty coater 14
5 and the platter 16 is subsequently inserted into the coater 14.

6 Referring to FIG.2, when the platter 16 is inserted into the
7 coater 14, the actuating cylinders 78 actuate the contactor 32 into
8 contact (physical and electrical) with the cathode 36 and the vessel 24
9 is closed. The mechanical rough vacuum pump 50 is subsequently
10 operated to evacuate the vessel to a predetermined pressure. Once that
11 pressure is reached, the high-volume diffusion vacuum pump 52 is
12 operated to further evacuate the vessel 24 to near vacuum conditions.
13 The substrates 12 are then cleaned of any remaining contaminants
14 and/or oxidation by a method such as "sputter cleaning". Sputter
15 cleaning is a process well known in the art and will not be described in
16 detail here. Other cleaning methods may be used alternatively. While
17 the substrates 12 are cleaned, the contaminants are purged typically
18 using an inert gas.

19 Prior to initiating an arc several steps are completed, including:
20 (1) the biasing source 118 is activated and the substrates 12 are
21 electrically biased; (2) the substrates 12 are placed in motion at a
22 particular rotational speed; (3) the power supply 54 is set to establish
23 an arc having a particular magnitude of current and voltage, but no arc
24 is initiated; (4) the vacuum pumps 50,52 establish and maintain a
25 particular vacuum pressure of gas within the vessel 24; and (5) coolant
26 flows are established through the vessel cooling passages 44 and the
27 contactor cooling passages 46. Specific process parameters will depend
28 upon factors such as the substrate 12 material, the material to be
29 coated, and the desired characteristics of the coating, etc.

This is the replacement sheet

Date: 30 NOV 1998

1 Once the aforementioned steps have been completed, the arc
2 initiator 56 causes an arc to jump between the cathode 36 and the
3 deflector shields 82 electrically connected to the anodic vessel 24. The
4 magnetic field generator 74 subsequently drives the arc along an arc
5 path 142 (see FIG.3) around the evaporative surface 88 of the cathode
6 36. The energy delivered by the arc causes the material at the cathode
7 spot to vaporize, thereby liberating atoms, molecules, ions, electrons,
8 and particles from the cathode 36. FIG.3 shows an eroded cathode 36
9 in phantom. The erosion is substantially symmetrical relative to the arc
10 path 142. The biased substrates 12 attract the ions, causing them to
11 accelerate toward the substrates 12, attach and collectively form a
12 coating of the cathode material. Rotation of the substrates 12 relative
13 to the cathode 36 promotes uniform deposition of the coating on the
14 substrate 12. Coolant passing through the contactor 32 directly cools
15 the contactor 32, and indirectly cools the cathode 36. When a coating
16 of sufficient thickness has been deposited on the substrates 12, the
17 power supply 54 is turned off and the arc extinguished. The vessel 24
18 is purged with inert gas and brought to ambient pressure. The
19 contactor 32 is actuated out of contact with the cathode 36, the vessel
20 24 opened, and the platter 16 is removed from the vessel 24 and placed
21 onto the shuttle car 122.

22 Referring to FIG.1, during the coating run, the empty shuttle
23 car 122 returns to the platter docking station 18 and the second platter
24 16 is transported across the shuttle car 122 to the first dock 130. The
25 shuttle car 122 then travels to the next coater 14 to be emptied,
26 receives the platter 16 bearing coated substrates 12 and transports the
27 platter 16 to the platter docking station 18, where the platter 16 is
28 transferred to the second dock 132. Thus, the cycle of coating
29 substrates 12 repeats itself.

This is the replacement sheet

Date: 30 NOV 1998

1 The controller 140 provides the command logic for coordinating
2 the tasks of transporting platters 16 along the shuttle track 20, and
3 within the platter docking station 18. For example, the operator (not
4 shown) enters a command to transport the shuttle car 122 bearing a
5 platter 16 from a particular coater 14 to the platter docking station 18.
6 The controller 140 compares the actual position of the loaded shuttle
7 car 122 with the stored reference value of the platter docking station 18
8 and commands the third drive unit (D3) to transport the shuttle car 122
9 to the platter docking station 18. A real time signal from the position
10 indicator sensing the actual position of the shuttle car 122 is sent to the
11 controller 140 until, the actual position signal coincides with the
12 reference value associated with the platter docking station 18. Similar
13 control logic is used to move the platters 16 in and out of the first 130
14 and second 132 docks and in and out of the coaters 14.

15 The controller 140 also provides the command logic for
16 operating each coater 14. The described steps of: (1) opening the
17 vessel 24; (2) actuating the contactor 32 into electrical contact with the
18 cathode 36; (3) operating the vacuum pumps 50,52 to evacuate the
19 coater 14; (4) biasing the substrates 12 via the biasing source 118; (5)
20 rotating the substrates 12 by driving the gears 106,108 attached to the
21 platter 16; (6) creating a potential difference between the cathode 36
22 and the anodic vessel 24 via the power supply 54; and (7) initiating an
23 arc between the cathode 36 and the deflector shields 82 (or vessel 24);
24 are all coordinated by commands stored within the controller 140. The
25 commands can be created and stored in the form of a software program
26 using a commercially available computer software programming
27 language.

28 Although this invention has been shown and described with
29 respect to the detailed embodiments thereof, it will be understood by
30 those skilled in the art that various changes in form and detail thereof

This is the replacement sheet

Date: 30 NOV 1998

1 may be made without departing from the spirit and the scope of the
2 invention. For example, the described platter docking station 18 is a
3 simplistic version capable of satisfying the present invention production
4 system 10. More complex systems capable of handling more than two
5 platters 16, such as a turret, may be used alternatively. Another
6 change from the best mode may be found in the drive units. For
7 example, a linear motor could be used to drive the shuttle car and
8 hydraulic actuators could be used to move a platter 16 on and off the
9 shuttle car 122.

This is the replacement sheet

Date: 30 NOV 1998



We claim:

- 1 1. A vapor deposition production system for coating substrates,
2 comprising:
3 a plurality of vapor deposition coaters;
4 a plurality of platters;
5 a platter docking station;
6 a shuttle track, connecting said docking station and said coaters;
7 means for transporting said platters between said coaters and
8 said docking station;
9 wherein said platters are selectively transported between said
10 coaters and said docking station via said shuttle track, and into, and out
11 of, said coaters.

- 1 2. A vapor deposition production system according to claim 1,
2 further comprising:
3 a controller, having a central processing unit, connected to said
4 coaters and said means for transporting said platters, wherein said
5 controller controls the operation of said coaters and the operation of
6 said means for transporting said platters.

- 1 3. A vapor deposition production system according to claim 2,
2 wherein said means for transporting said platters between said coaters
3 and said docking station, comprises:
4 a shuttle car, adapted for travel along said shuttle track, having
5 a drive means for propelling said shuttle car.

- 1 4. A vapor deposition production system according to claim 3,
2 wherein each said coater comprises:
3 a vessel;
4 means for maintaining a vacuum in said vessel;

This is the replacement sheet

Date: 30 NOV 1998



5 a cathode, mounted on one of said platters;
6 a contactor, positioned inside said vessel;
7 means for selectively sustaining an arc of electrical energy
8 between said cathode and an anode, wherein said means for selectively
9 sustaining an arc of electrical energy is electrically connected to said
0 contactor; and
1 an actuator, wherein said actuator selectively actuates said
2 contactor into contact with said cathode, and thereby electrically
3 connects said cathode to said means for sustaining an arc of electrical
4 energy;
5 wherein said controller controls operation of said means for
6 maintaining a vacuum in said vessel, and said means for selectively
7 sustaining an arc of electrical energy, and said actuator.

1 5. A vapor deposition production system according to claim 4,
2 wherein said cathode is disk-shaped having a pair of end surfaces
3 connected by an evaporative surface;
4 wherein said actuator actuates said contactor into contact with
5 one of said end surfaces of said cathode, thereby electrically connecting
6 said cathode to said means for selectively sustaining an arc of electrical
7 energy.

1 6. A vapor deposition production system according to claim 5,
2 wherein said coater further comprises means for driving said arc around
3 said evaporative surface, wherein said means for driving said arc is
4 positioned in close proximity to said cathode, and said means for
5 driving said arc produces a magnetic field that permeates said cathode.

1 7. A vapor deposition production system according to claim 4,
2 wherein said cathode is annular-shaped having a pair of end surfaces,



3 and an evaporative surface and a bore extending between said end
4 surfaces;

5 wherein said actuator actuates said contactor into electrical
6 contact with said cathode, thereby electrically connecting said cathode
7 to said means for selectively sustaining an arc of electrical energy.

1 8. A vapor deposition production system according to claim 7,
2 wherein said coater further comprises means for driving said arc around
3 said evaporative surface, wherein said means for driving said arc is
4 positioned within said bore of said cathode, and said means for driving
5 said arc produces a magnetic field that permeates said cathode.

1 9. A vapor deposition production system according to claim 4,
2 wherein said contactor comprises:
3 a head, positioned inside said vessel;
4 a shaft, attached to said head, extending from said head to
5 outside said vessel.

1 10. A vapor deposition production system according to claim 9,
2 wherein said platter further comprises selectively rotatable pedestals,
3 for supporting the substrates.

1 11. A vapor deposition production system according to claim 10,
2 further comprising:
3 a biasing source, for electrically biasing the substrates attached
4 to said platters positioned within said coaters;
5 means for electrically connecting said biasing source to the
6 substrates.



1 12. A vapor deposition production system according to claim 11,
2 wherein said means for electrically connecting said biasing source to
3 the substrates electrically connects said biasing source to said platter,
4 and said platter is electrically connected to the substrates.

1 13. A vapor deposition production system according to claim 12,
2 wherein said cathode is disk-shaped having a pair of end surfaces
3 connected by an evaporative surface;
4 wherein said actuator actuates said contactor into contact with
5 one of said end surfaces of said cathode, thereby electrically connecting
6 said cathode to said means for selectively sustaining an arc of electrical
7 energy.

1 14. A vapor deposition production system according to claim 13,
2 wherein said coater further comprises means for driving said arc around
3 said evaporative surface, wherein said means for driving said arc is
4 positioned in close proximity to said cathode, and said means for
5 driving said arc produces a magnetic field that permeates said cathode.

1 15. A vapor deposition production system according to claim 12,
2 wherein said cathode is annular-shaped having a pair of end surfaces,
3 and an evaporative surface and a bore extending between said end
4 surfaces;
5 wherein said actuator actuates said contactor into electrical
6 contact with said cathode, thereby electrically connecting said cathode
7 to said means for selectively sustaining an arc of electrical energy.

1 16. A vapor deposition production system according to claim 15,
2 wherein said coater further comprises means for driving said arc around
3 said evaporative surface, wherein said means for driving said arc is



- 4 positioned within said bore of said cathode, and said means for driving
5 said arc produces a magnetic field that permeates said cathode.

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Date: **30 NOV 1998**

Vapor Deposition Production Coating System

ABSTRACT OF THE DISCLOSURE

A vapor deposition production system for coating substrates is provided which includes a plurality of vapor deposition coaters, a plurality of platters, a platter docking station, a shuttle track, and apparatus for transporting the platters between the coaters and the platter docking station. The shuttle track connects the platter docking station and the coaters. Platters selectively removed from the coaters are transported along the shuttle track to the platter docking station where processed substrates are unloaded from the platters and unprocessed substrates loaded on to the platters.

(Figure 1)

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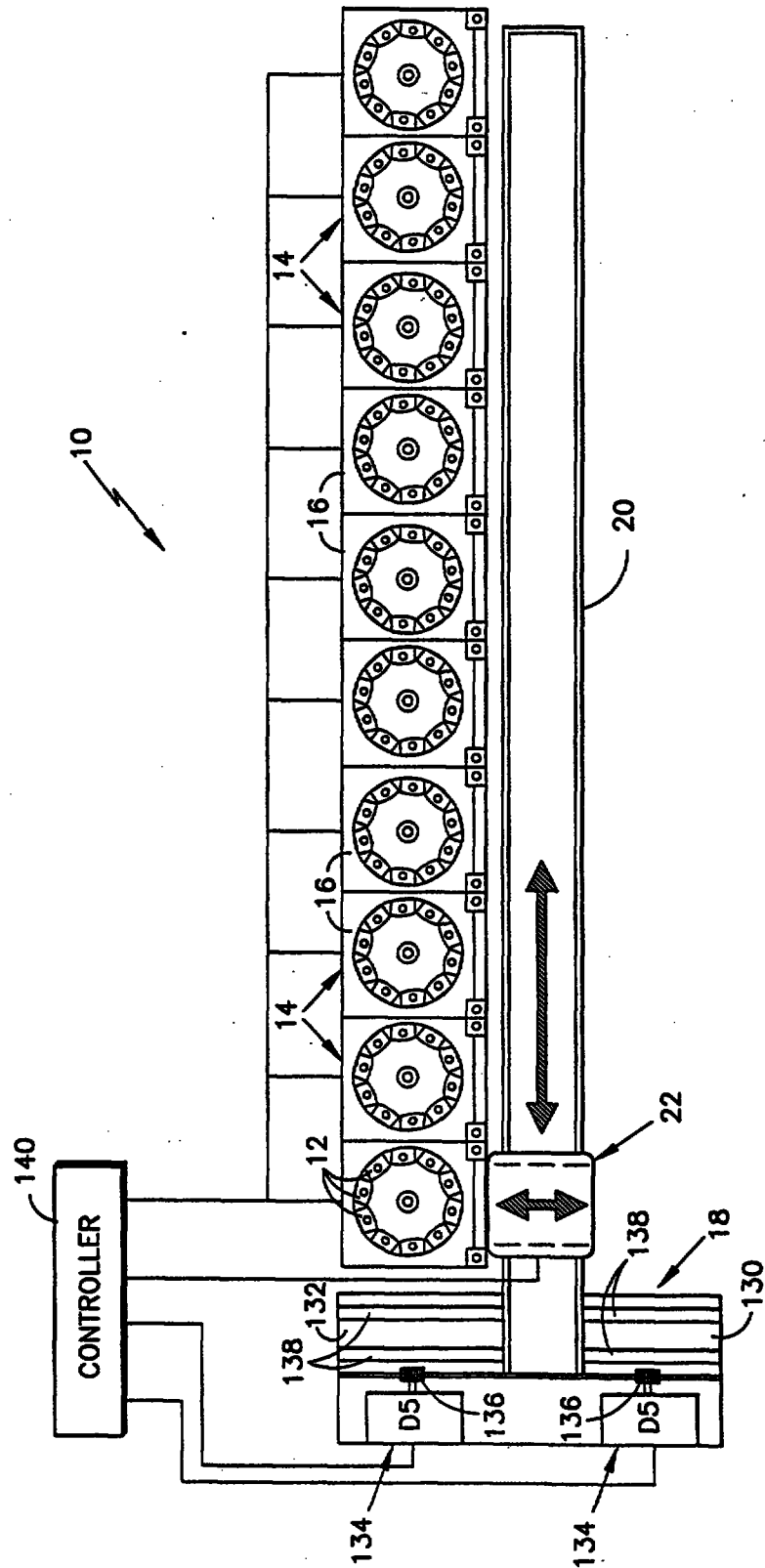


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30 NOV 1998

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FIG. 1



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Date: 30 NOV 1998

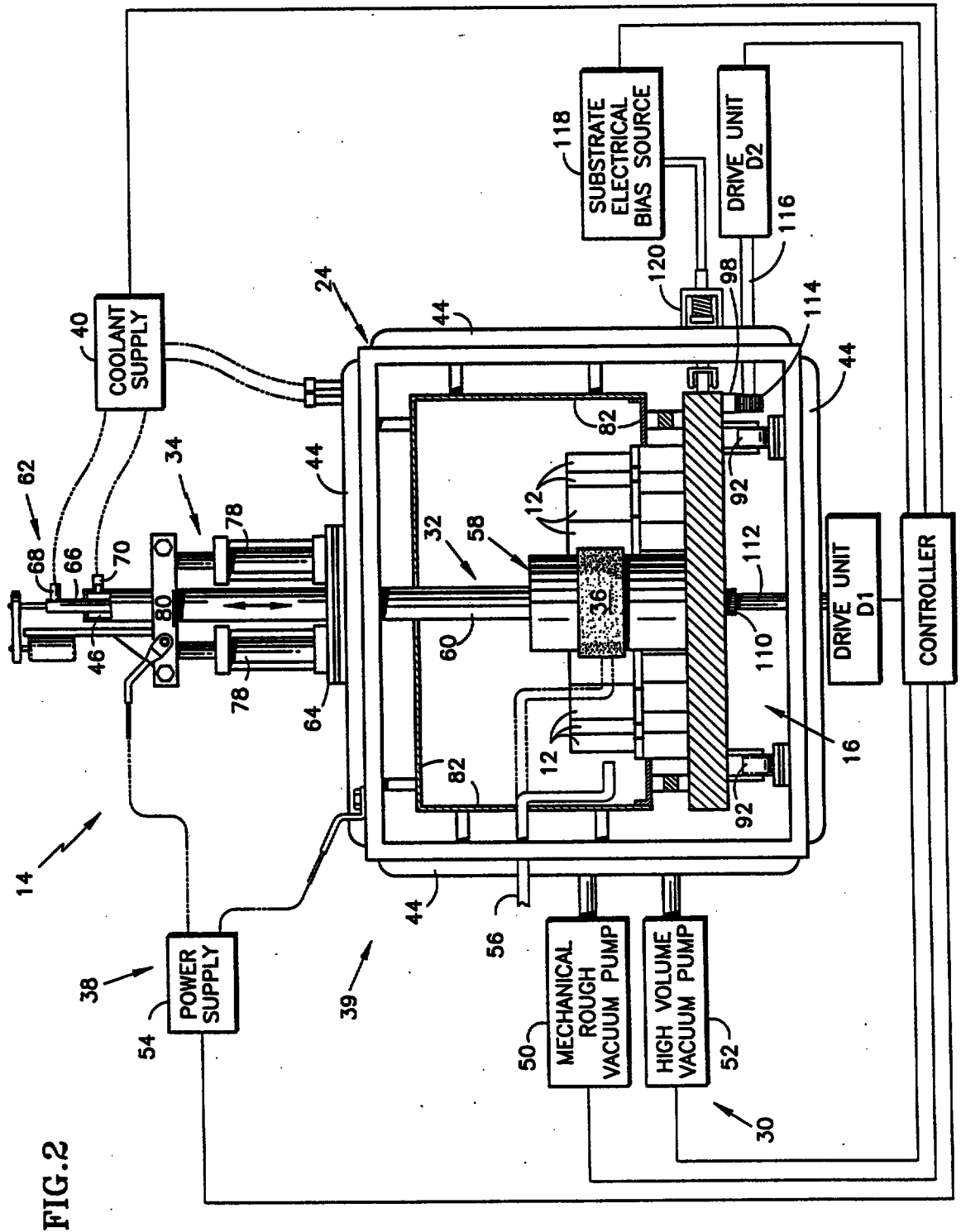


FIG. 2

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Date: 30 NOV 1998

FIG.3

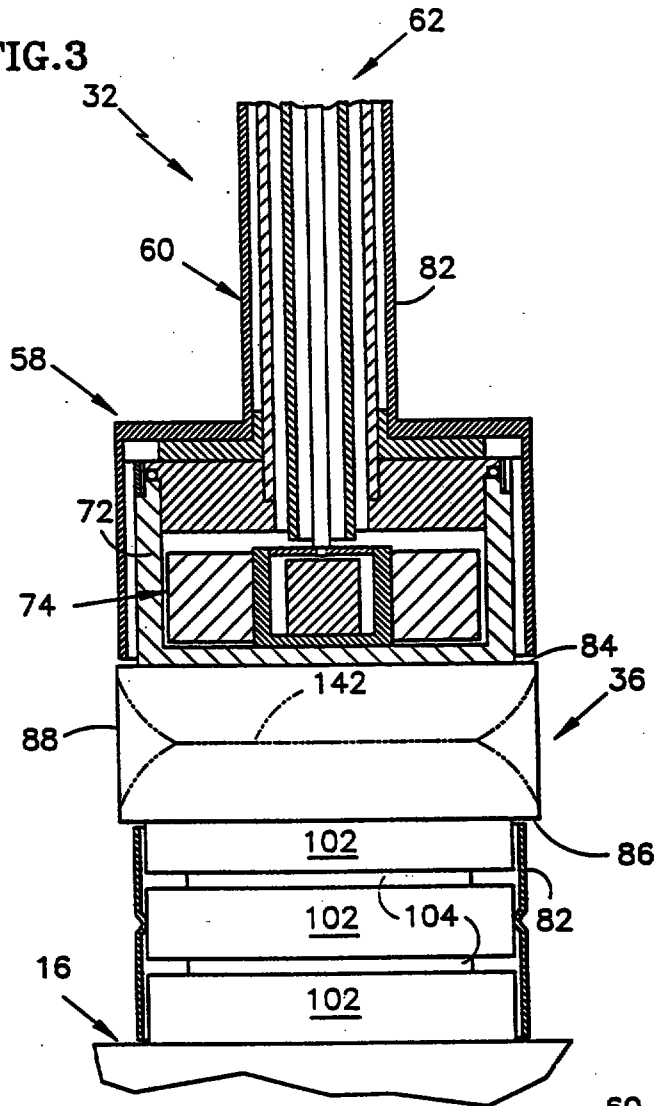
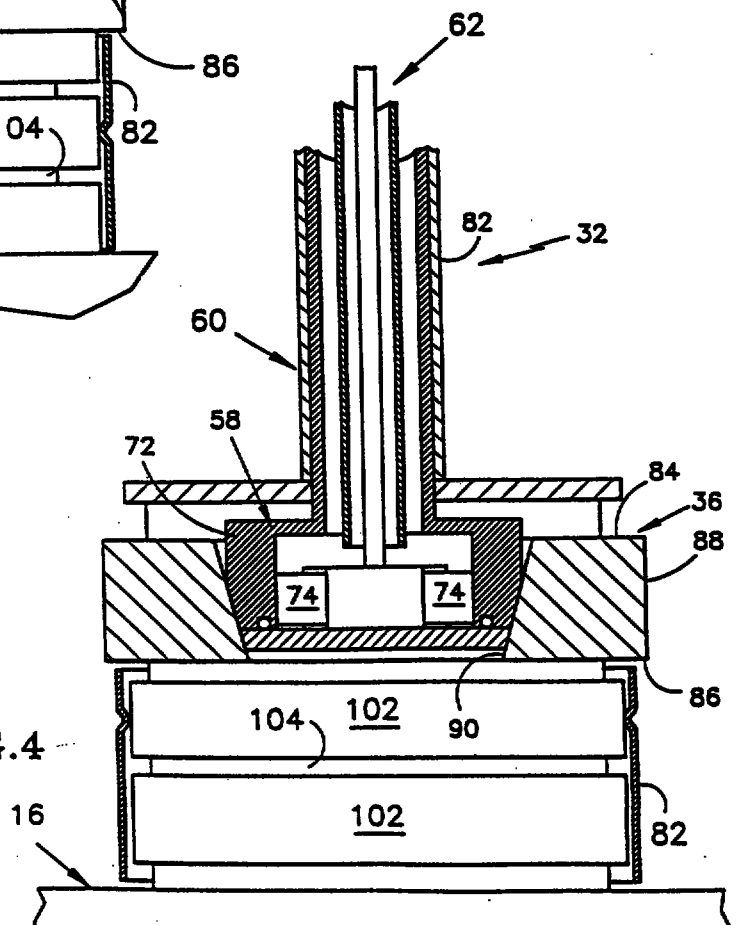


FIG.4



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Date: 30 NOV 1998

FIG.5

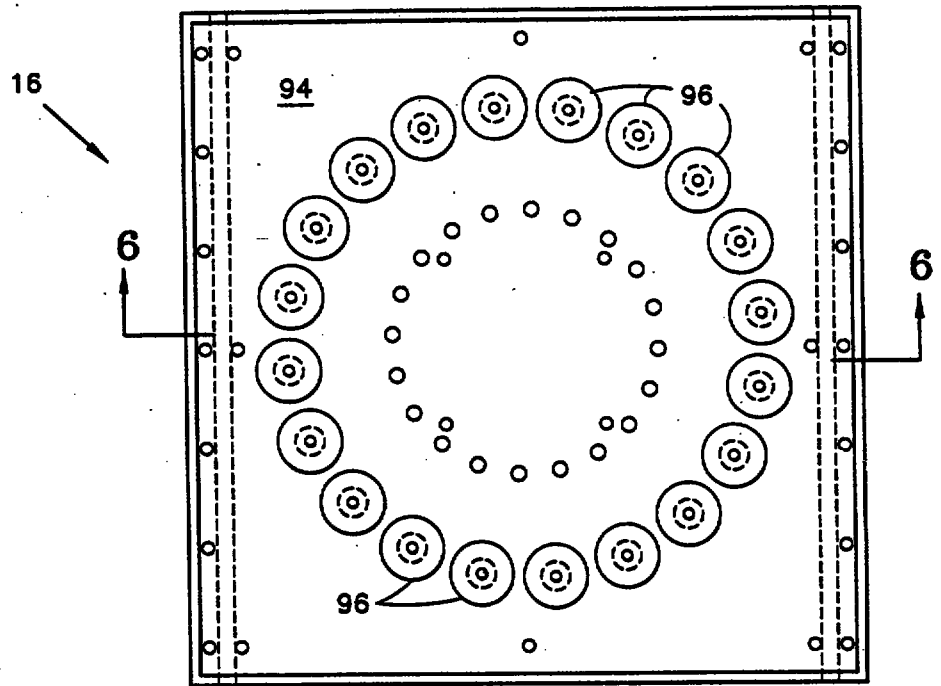
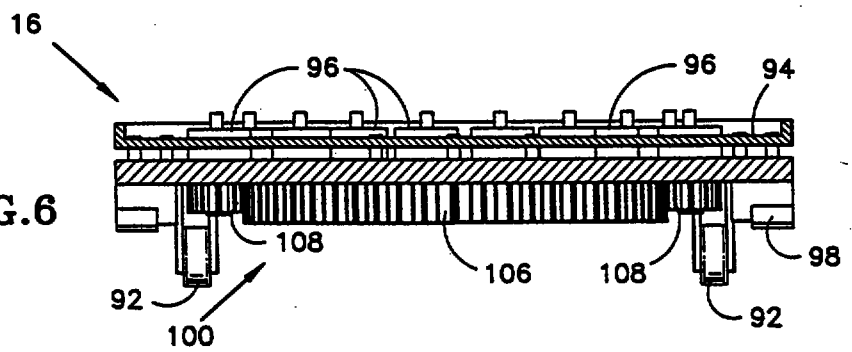
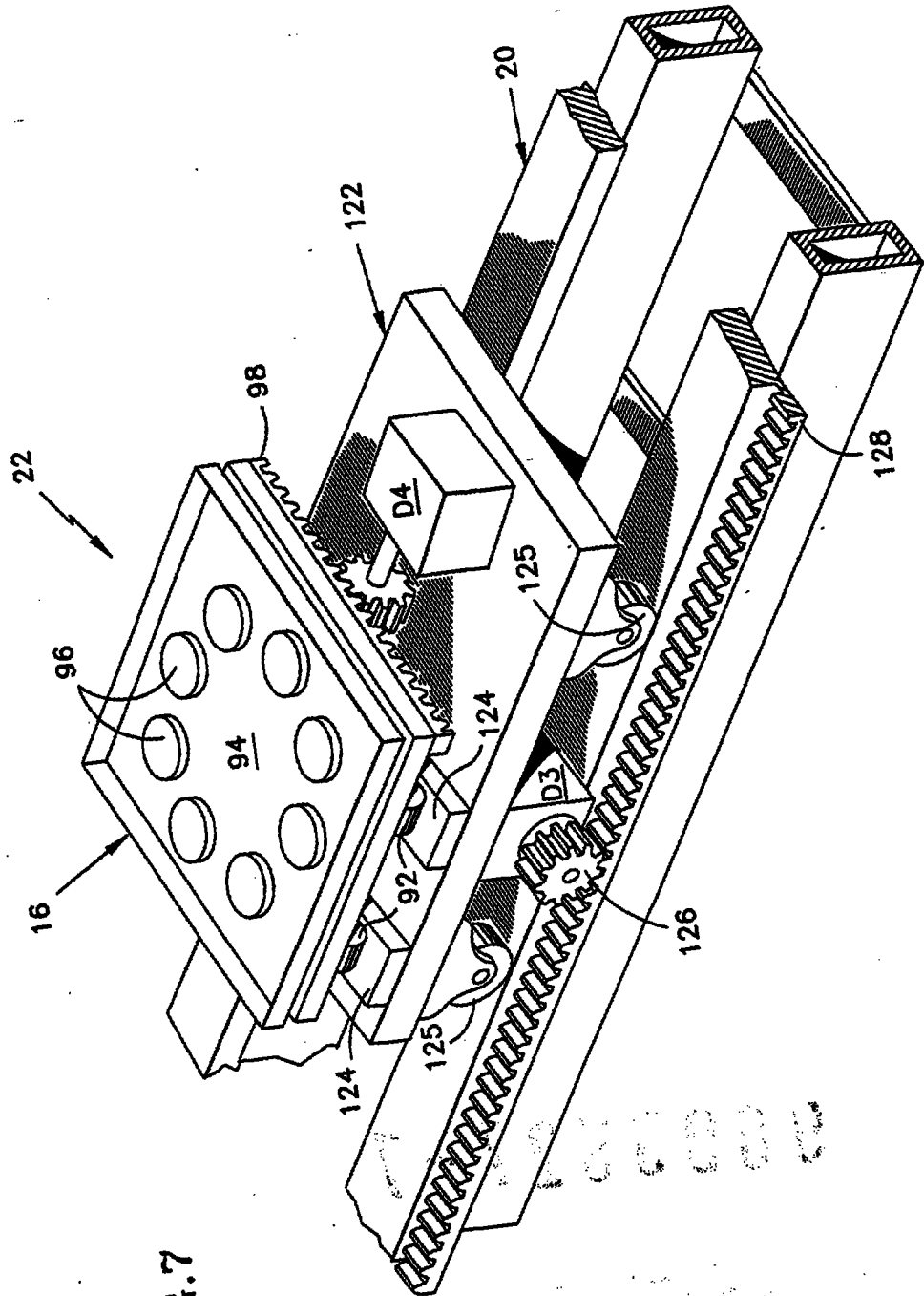


FIG.6



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Date: 30 NOV 1998



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Date: 30 NOV 1998



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TEXT OF THE ABSTRACT

VAPOR DEPOSITION PRODUCTION COATING SYSTEM

A vapor deposition production system (10) for coating substrates (12) is provided which includes a plurality of vapor deposition coaters (14), a plurality of platters (16), a platter docking station (18), a shuttle track (20), and apparatus (22) for transporting the platters (16) between the coaters (14) and the platter docking station (18). The shuttle track (29) connects the platter docking station (18) and the coaters (14). Platters selectively removed from the coaters are transported along the shuttle track to the platter docking station where processed substrates are unloaded from the platters and unprocessed substrates loaded on to the platters.

Figure 1.

REPLACEMENT SHEET

16 JUL 1999